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263160US41PCTSERIAL NO.  
10/517,616

## LIST OF REFERENCES CITED BY APPLICANT

APPLICANT

Gabriel NAVARRO NIEDERCORN

FILING DATE

September 27, 2005

GROUP

3754

## U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AA	5,783,268	07-21-1998	Noonan et al.			
	AB	5,750,225	05-12-1998	Petty			
	AG	5,040,297	08-20-1991	Scheinost			
	AD	4,183,379	01-15-1980	Marquette et al.			
	AE	4,179,808	12-25-1979	Smith			
	AF	4,064,627	12-27-1977	Zanfini			
	AG	4,064,626	12-27-1977	Meshulam et al.			
	AH	3,092,529	06-04-1963	A. J. Pearson			
	AI	2001/0003993	06-21-2001	Faverio, IV et al.			
	AJ						
	AK						
	AL						
	AM						
	AN						

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION	
					YES	NO
	AO	DE 1 190 391	04-01-1965	Germany	X	
	AP	FR 2 409 855	06-22-1979	France (English Abstract)		X
	AD	FR 2 740 804	05-09-1997	France (English Abstract)		X
	AR	GB 2 189 273	10-21-1987	Great Britain		
	AS					
	AT					
	AU					
	AV					

## OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)

	AW	NAIMA (North American Insulation Manufacturers Association); Fibrous Glass Duct Construction Standards, 5 <sup>th</sup> Edition, Low Velocity Systems 2 Inches (500Pa) Maximum Static Pressure, 2002; pgs. 133				
	AX	Johns Manville, Air Handling Systems Micro-Aire Duct Board, 2 pgs.				
	AY	Notice of Opposition to a European Patent; EP1532391; granted March 18, 2009; Insulation Panel for Supply Duct; 7 pgs.				
	AZ	Opposition against European patent EP1532391 B1; Opponent: Knauf Insulation Technology; Arguments in Support of Opposition; 9 pgs.			<input type="checkbox"/> Additional References sheet(s) attached	

Examiner

Date Considered

\*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.